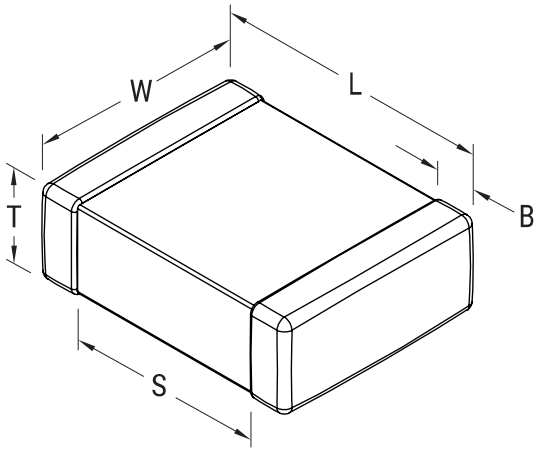
C0805C332G2GEC7210

ESD SMD Comm C0G, Ceramic, 3,300 pF, 2%, 200 VDC, C0G, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805 / 2012



Click here for the 3D model.

General Information	
Series	ESD SMD Comm C0G
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
Typical Component Weight	11 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
T	0.78mm +/-0.10mm
S	0.7mm MIN
B	0.5mm +/-0.25mm
Case Code (EIA / mm)	0805 / 2012

Packaging Specifications	
Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	15000

Specifications	
Capacitance	3,300 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	2%
Voltage DC	200 VDC
ESD Level per AEC-Q200	16,000 V ESD Level
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	C0G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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